

Title (en)
MODULAR BUILDING SYSTEM AND USE

Title (de)
MODULARES BAUSYSTEM UND SEINE VERWENDUNG

Title (fr)
SYSTEME DE CONSTRUCTION MODULAIRE ET SON UTILISATION

Publication
EP 1226317 B1 20051123 (EN)

Application
EP 00932266 A 20000510

Priority
• US 0012795 W 20000510
• US 13330699 P 19990510
• US 18525000 P 20000225

Abstract (en)
[origin: WO0068523A1] A modular building system (100) including preformed extrusion-molded polymeric material (116). Parts include integral connector elements (160, 162) which can be slidably and snappingly reversibly interconnected to form the basic frame (102) and panel structures (108) of an overall building. The interconnected region permits limited ranges of angular as well as translational relative motion between adjacent, connected elements. Parts are assembled simply and quickly in the field, without requiring skilled labor or specialized tools, to form a functionally solid and stable building which responds to loads and temperature changes with yieldable, accommodating deformations that minimize the likelihood of building structural damage, and effectively transmit necessary loads to the ground via load-transfer paths through the building.

IPC 1-7
E04B 1/343; **E04H 9/02**

IPC 8 full level
E02D 27/00 (2006.01); **A62C 35/02** (2006.01); **E02D 27/01** (2006.01); **E04B 1/02** (2006.01); **E04B 1/08** (2006.01); **E04B 1/14** (2006.01); **E04B 1/343** (2006.01); **E04B 1/62** (2006.01); **E04B 5/48** (2006.01); **E04B 7/22** (2006.01); **E04C 3/02** (2006.01); **E04C 3/28** (2006.01); **E04C 3/29** (2006.01); **E04H 9/02** (2006.01); **E06B 1/00** (2006.01); **E04B 1/00** (2006.01)

CPC (source: EP)
A62C 35/02 (2013.01); **E02D 27/01** (2013.01); **E04B 1/14** (2013.01); **E04B 5/48** (2013.01); **E04B 7/22** (2013.01); **E04C 3/02** (2013.01); **E04C 3/28** (2013.01); **E04C 3/29** (2013.01); **E06B 1/00** (2013.01); **E04B 1/0007** (2013.01)

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 0068523 A1 20001116; AT E310859 T1 20051215; AU 5000900 A 20001121; AU 775847 B2 20040819; CA 2373111 A1 20001116; CN 1360657 A 20020724; DE 60024303 D1 20051229; DE 60024303 T2 20060817; DK 1226317 T3 20060403; EP 1226317 A1 20020731; EP 1226317 A4 20030514; EP 1226317 B1 20051123; ES 2256009 T3 20060716; JP 2003527500 A 20030916; MX PA01011421 A 20040812; NZ 515308 A 20040130

DOCDB simple family (application)
US 0012795 W 20000510; AT 00932266 T 20000510; AU 5000900 A 20000510; CA 2373111 A 20000510; CN 00809946 A 20000510; DE 60024303 T 20000510; DK 00932266 T 20000510; EP 00932266 A 20000510; ES 00932266 T 20000510; JP 2000617286 A 20000510; MX PA01011421 A 20000510; NZ 51530800 A 20000510